

# EPS Webinar Series 2021

## *Sintered Silver As Die Attach Materials*

This talk introduces the motivation for using sintered silver (Ag) as die-attach material and associated processes used in forming this Ag joint in bonding application. In addition, the talk also addresses the main factors influencing the mechanical properties (die shear strength) of the Ag joint, namely, sintering temperature, pressure, time, heating rate, atmosphere, substrate metallization and its roughness, and die-size. Comparison with sintered Cu is also included in this talk. This talk is expected to be useful to those new to this die attach materials and interested to explore this bonding technique further in their process

**Date: 6 July 2021 (Tuesday)**

**Time: 10.00-11.00 a.m. (M'sia Time, GMT +8:00)**

**Platform: CISCO WebEx**

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*\*E-certificates will be provided to all participant*



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**Dr. Siow Kim Shyong**

Research Fellow / Senior Lecturer  
Institute of Microengineering and  
Nanoelectronics, UKM  
IEEE CPMT Malaysia Chairperson from  
Y2014-2016

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## EPS Malaysia Webinar Series 2021

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Dr. Siow Kim Shyong is a Research Fellow at the Institute of Microengineering and Nanoelectronics, Universiti Kebangsaan Malaysia. With 10 years theoretical and practical experiences in sintered bonding, he has published extensively. His most recent book is Die Attach Materials for High Temperature Applications in Microelectronics Packaging (Springer-Nature), 2018 .



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- Sintered silver (Ag) as die-attach material and associated processes used in forming this Ag joint in bonding application will be discussed.
- The talk will address the main factors influencing the mechanical properties of sintered materials.
  - Comparison between Cu and sintered silver (Ag) is included in this talk.

It is **FREE!** Enroll yourself and join us in this exciting webinar. See you there !